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(54) **Title:** SYSTEMS AND METHODS FOR PURIFYING SOLVENTS

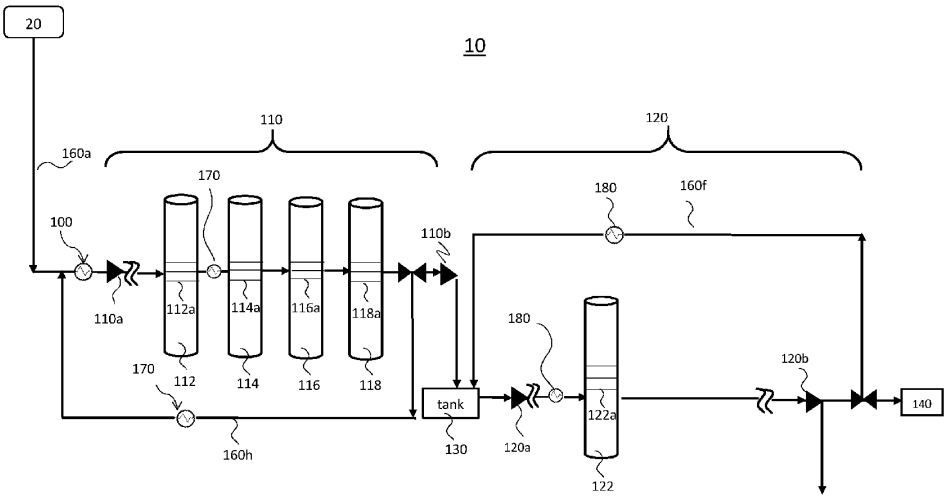

Figure 1

(57) **Abstract:** The present disclosure is directed to methods and systems of purifying solvents. The purified solvents can be used for cleaning a semiconductor substrate in a multistep semiconductor manufacturing process.

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